

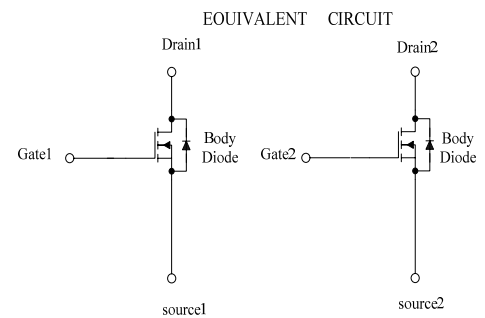
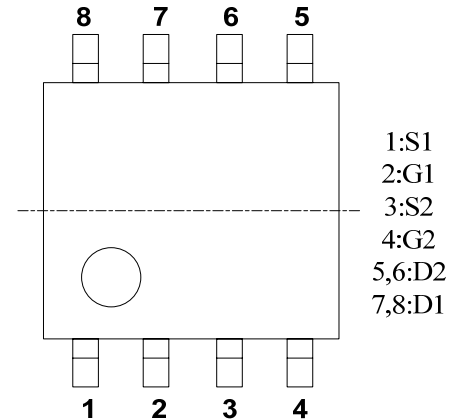


### General Description

The AM9945N uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge. This device is suitable for use as DC-DC converters and power managements in portable and battery-powered products.

### Features

- $V_{DS}$  (V) =60V
- Low on-state resistance  
 $R_{DS(on)} = 89 \text{ m}\Omega$  MAX ( $V_{GS} = 10\text{V}$ ,  $I_D = 3.6\text{A}$ )  
 $R_{DS(on)} = 104 \text{ m}\Omega$  MAX ( $V_{GS} = 4.5\text{V}$ ,  $I_D = 3.4\text{A}$ )
- Fast switching speed



### Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$ )

PARAMETER	SYMBOL	LIMIT	UNIT
Drain to Source Voltage	$V_{DSS}$	60	V
Gate to Source Voltage	$V_{GSS}$	$\pm 20$	V
Drain Current (DC) <sup>a</sup>	$T_A=25^\circ\text{C}$	$\pm 3.6$	A
	$T_A=70^\circ\text{C}$	$\pm 3.1$	
Drain Current (pulse) <sup>b</sup>	$I_{D(pulse)}$	$\pm 25$	A
Continuous Source Current (Diode Conduction) <sup>a</sup>	$I_S$	2	A
Maximum Power Dissipation <sup>a</sup>	$T_A=25^\circ\text{C}$	2.1	W
	$T_A=70^\circ\text{C}$	1.3	
Channel Temperature	$T_{ch}$	150	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS				
Parameter		Symbol	Maximum	Units
Maximum Junction-to-Ambient <sup>a</sup>	$t \leq 10\text{sec}$	$R_{\theta JA}$	62.5	$^\circ\text{C/W}$
	$t \leq 5\text{sec}$		110	$^\circ\text{C/W}$

**Note a.** Mounted on FR4 Board of 1"x1".

**b.** Pulse width limited by maximum junction temperature

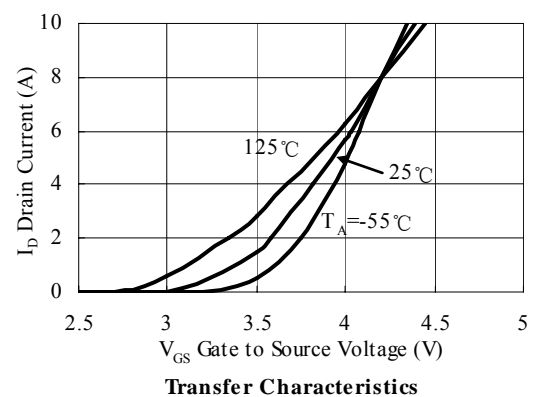
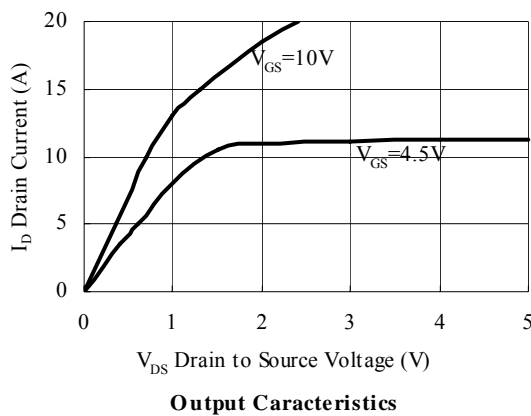
**Caution:** These values must not be exceeded under any conditions.

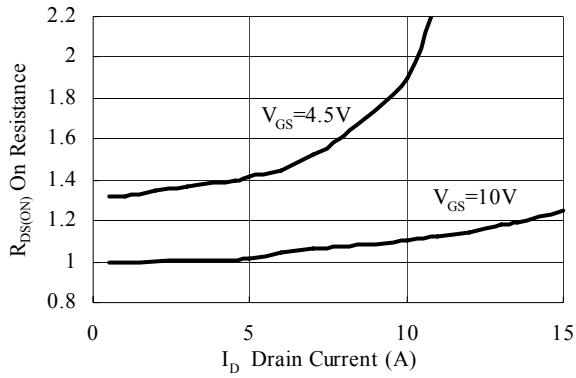
### Ordering Information

- Part Number: AM9945N
- Package: SOIC8

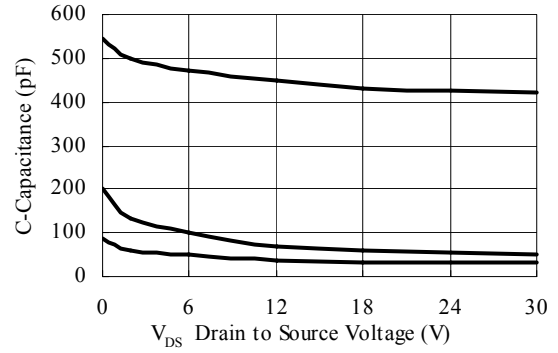
**Electrical Characteristics (T<sub>A</sub> = 25°C)**

CHARACTERISTICS	SYMBOL	TEST CONDITION	MIN.	Typ.	MAX	Unit
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V,			1	uA
		V <sub>DS</sub> =60V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C			10	
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =20V			±100	nA
Gate Cut-off Voltage	V <sub>GSS(off)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	1			V
On-State Drain Current	I <sub>D(on)</sub>	V <sub>DS</sub> =5V, V <sub>GS</sub> =10V	20			A
Drain -Source On-Resistance	R <sub>DS(on)1</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =3.6A			89	mΩ
	R <sub>DS(on)2</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =3.4A			104	
Forward Transfer Admittance	y <sub>fs</sub>	V <sub>DS</sub> =15V, I <sub>D</sub> =3.6A		11		S
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =2.0A, V <sub>GS</sub> =0A		1.1		V
Pulsed Source Current (Body Diode)	I <sub>SM</sub>			3.5		A
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =30V, R <sub>L</sub> =30Ω, I <sub>D</sub> =1A, V <sub>GEN</sub> =10V		9		nS
Rise Time	t <sub>r</sub>			10		
Turn-Off Delay Time	t <sub>d(off)</sub>			21		
Fall-Time	t <sub>f</sub>			8		
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =3.6A		3.6		nC
Gate-Source Charge	Q <sub>gs</sub>			1.8		
Gate-Drain Charge	Q <sub>gd</sub>			1.3		

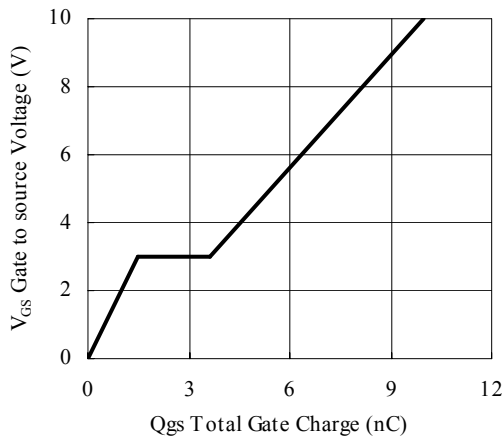
**Typical characteristics (25°C unless noted)**




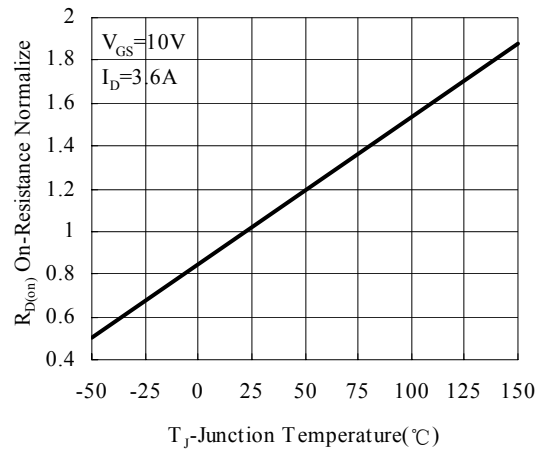
On Resistance VS Drain Current



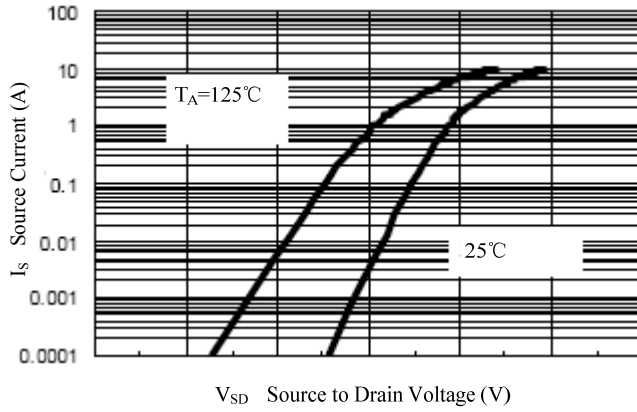
Capacitance



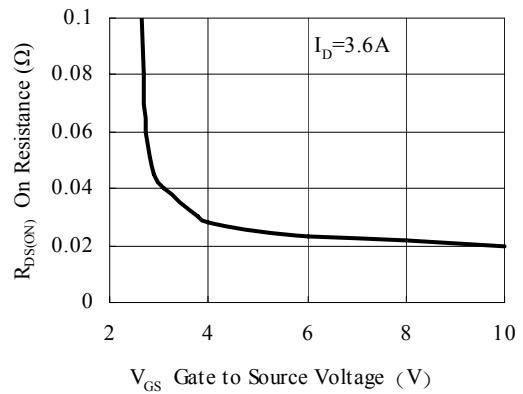
Gate Charge



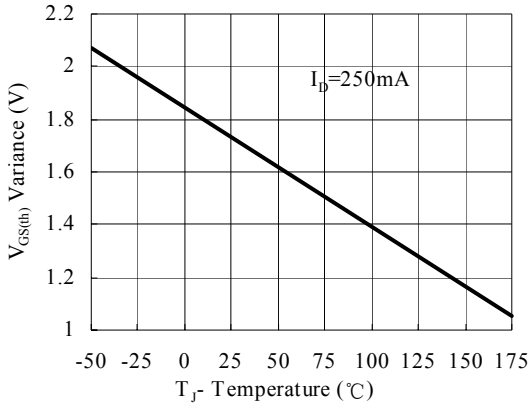
On-Resistance vs Junction Temperature



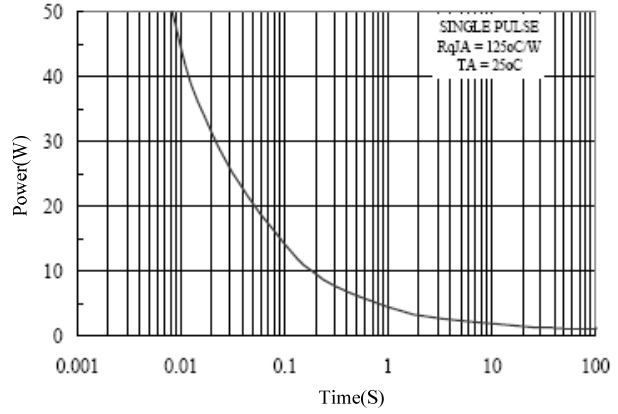
Source-Drain Diode Forward Voltage



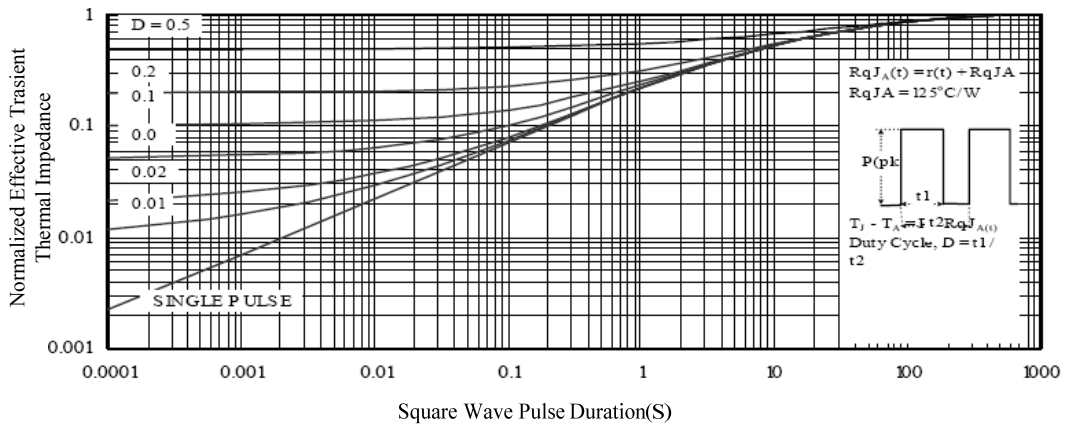
On-Resistance VS Gate to Source Voltage



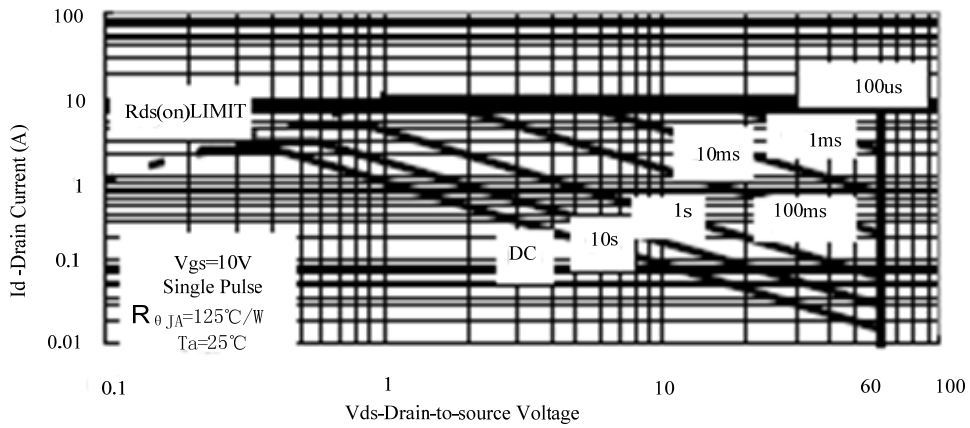
Threshold Voltage



Single Pulse Power



Normalized Thermal Transient Impedance, Junction to Ambient

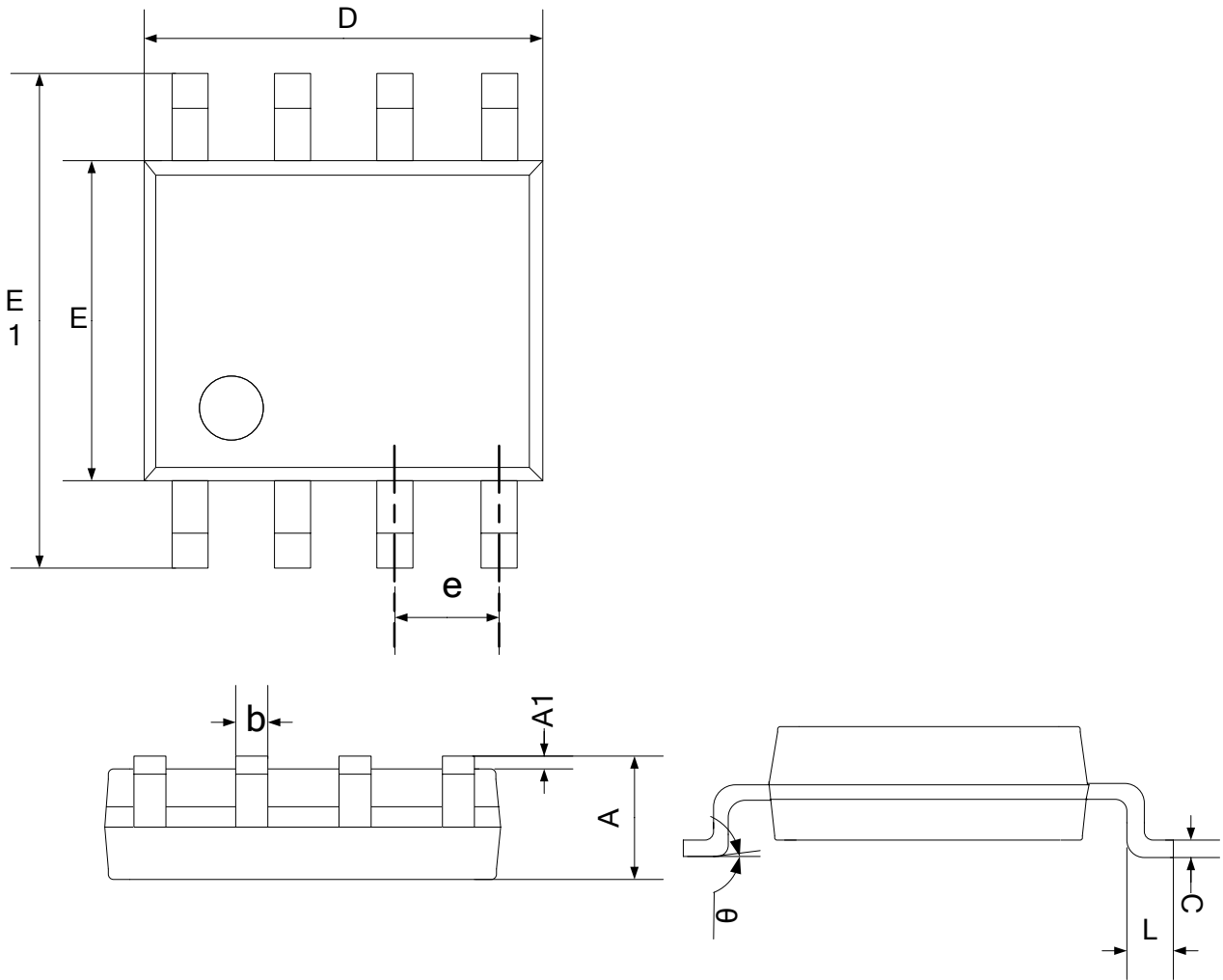


Maximum Safe Operating Area

# Package Drawing

SOIC8

UNIT (mm)



## Dimensions

	D	E	A	E1	A1	C	L	b	e	$\theta$
Min.	4.80	3.80	1.35	5.80	0.100	0.19	0.500	0.380	1.27 BSC	0°
Nom.	4.90	3.90	1.55	6.00	0.175	0.22	0.715	0.445		4°
Max.	5.00	4.00	1.75	6.20	0.250	0.25	0.930	0.510		8°